



Miniature Package from Diodes Incorporated Reduces Logic Footprint

Plano, Texas – March 19, 2014 – Diodes Incorporated (Nasdaq: DIOD), a leading global manufacturer and supplier of high-quality application specific standard products within the broad discrete, logic and analog semiconductor markets, today introduced two families of single-gate logic parts in one of the world's smallest packages, the DFN0808. With a 0.8mm square footprint and an off-board height of 0.35mm, the miniature 74AUP1G and 74LVC1G logic devices deliver significant space and weight savings to portable consumer electronic products, such as cell phones and tablets.

With its unique diamond pin configuration which maintains an equivalent lead spacing of 0.5mm, the DFN0808 package removes the need for specialized solder stencils. Diodes Incorporated is initially launching fourteen 74AUP1G parts and eleven 74LVC1G parts in the new package option.

The 74LVC1G products operate over a wide supply range of 1.6V to 5.5V and will interface directly with TTL levels. While operating over a lower supply range, from 0.8V to 3.6V, the 74AUP1G products can achieve a lower power consumption to help boost battery cell lifetime.

Both of these industry-standard logic families feature the following functions: AND, NAND, OR, XOR, inverters (simple, open-drain output and Schmitt trigger variants), and buffers (open-drain output, Schmitt trigger and tri-state output variants). NOR, AND with open-drain output, and a simple buffer are also available in the 74AUP1G logic family. For further information, visit the Company's website at www.diodes.com.

About Diodes Incorporated

Diodes Incorporated (Nasdaq: DIOD), a Standard and Poor's SmallCap 600 and Russell 3000 Index company, is a leading global manufacturer and supplier of high-quality application specific standard products within the broad discrete, logic and analog semiconductor markets. Diodes serves the consumer electronics, computing, communications, industrial, and automotive markets. Diodes' products include diodes, rectifiers, transistors, MOSFETs, protection devices, functional specific arrays, single gate logic, amplifiers and comparators, Hall-effect and temperature sensors; power management devices, including LED drivers, AC-DC converters and controllers, DC-DC switching and linear voltage regulators, and voltage references along with special function devices, such as USB power switches, load switches, voltage supervisors, and motor controllers. Diodes' corporate headquarters and Americas' sales office are located in Plano, Texas. Design, marketing, and engineering centers are located in Plano; San Jose, California; Taipei, Taiwan; Manchester, England; and Neuhaus, Germany. Diodes' wafer fabrication facilities are located in Kansas City, Missouri and Manchester, with four manufacturing facilities located in Shanghai, China, and two joint venture facilities located in Chengdu, China, as well as manufacturing facilities located in Neuhaus and Taipei. Additional engineering, sales, warehouse, and logistics offices are located in Fort Worth, Texas; Taipei; Hong Kong; Manchester; Shanghai; Shenzhen, China; Seongnam-si, South Korea; Suwon, South Korea; Tokyo, Japan; and Munich, Germany, with support offices throughout the world. For further information, including SEC filings, visit Diodes' website at <http://www.diodes.com>.

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Company Contact:

Diodes Incorporated
Julie Holland
VP, Worldwide Analog Products
P: 972-987-3900
E: pressinquiries@diodes.com

Investor Relations Contact:

Shelton Group
Leanne K. Sievers
EVP, Investor Relations
P: 949-224-3874
E: lsievers@sheltongroup.com